

Molding Type Module IGBT, 2-in-1 Package, 1200 V and 300 A



PRODUCT SUMMARY					
V _{CES}	1200 V				
I_C at $T_C = 80$ °C	300 A				
$V_{CE(on)}$ (typical) at $I_C = 300$ A, 25 °C	2.00 V				
Speed	8 kHz to 30 kHz				
Package	Double INT-A-PAK				
Circuit	Half bridge				

FEATURES

- 10 µs short circuit capability
- V_{CE(on)} with positive temperature coefficient
- Maximum junction temperature 150 °C
- · Low inductance case
- Fast and soft reverse recovery antiparallel FWD
- Isolated copper baseplate using DCB (Direct Copper Bonding) technology
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

TYPICAL APPLICATIONS

- UPS
- Inverter for motor drive
- · AC and DC servo drive amplifier

DESCRIPTION

Vishay's IGBT power module provides ultra low conduction loss as well as short circuit ruggedness. It is designed for applications such as general inverters and UPS.

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C unless otherwise noted)				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Collector to emitter voltage	V _{CES}		1200	V
Gate to emitter voltage	V _{GES}		± 20	V
Collector current		T _C = 25 °C	500	
Collector current I _C	IC	T _C = 80 °C	300	
Pulsed collector current	I _{CM} ⁽¹⁾	t _p = 1 ms	600	А
Diode continuous forward current	I _F	T _C = 80 °C	300	
Diode maximum forward current	I _{FM}	t _p = 1 ms	600	
Maximum power dissipation	P _D	T _J = 150 °C	1645	W
Short circuit withstand time	t _{SC}	T _J = 125 °C	10	μѕ
RMS isolation voltage	V _{ISOL}	f = 50 Hz, t = 1 min	2500	V

Note

⁽¹⁾ Repetitive rating: pulse width limited by maximum junction temperature.



IGBT ELECTRICAL SPECIFICATIONS (T _C = 25 °C unless otherwise noted)						
PARAMETER	SYMBOL	YMBOL TEST CONDITIONS MIN. TYP.		TYP.	MAX.	UNITS
Collector to emitter breakdown voltage	V _{(BR)CES}	T _J = 25 °C	1200	-	-	
Collector to emitter voltage	V _{CE(on)}	$V_{GE} = 15 \text{ V}, I_{C} = 300 \text{ A}, T_{J} = 25 ^{\circ}\text{C}$	-	2.00	2.45] ,
Collector to entitler voltage		V _{GE} = 15 V, I _C = 300 A, T _J = 125 °C	-	2.20	-	\ \ \
Gate to emitter threshold voltage	V _{GE(th)}	$V_{CE} = V_{GE}$, $I_{C} = 12$ mA, $T_{J} = 25$ °C	5.0	6.2	7.0	
Collector cut-off current	I _{CES}	$V_{CE} = V_{CES}$, $V_{GE} = 0$ V, $T_{J} = 25$ °C	-	-	5.0	mA
Gate to emitter leakage current	I _{GES}	$V_{GE} = V_{GES}$, $V_{CE} = 0$ V, $T_{J} = 25$ °C	-	-	400	nA

SWITCHING CHARACTERISTICS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Turn-on delay time	t _{d(on)}		-	574	-	
Rise time	t _r	1	-	133	-	ns mJ
Turn-off delay time	t _{d(off)}	$V_{CC} = 600 \text{ V}, I_{C} = 300 \text{ A}, R_{g} = 4.7 \Omega,$	-	563	-	
Fall time	t _f	$V_{GE} = \pm 15 \text{ V}, T_{J} = 25 \text{ °C}$	-	120	-	
Turn-on switching loss	E _{on}	7	-	23.9	-	
Turn-off switching loss	E _{off}	7	-	25.3	-	
Turn-on delay time	t _{d(on)}		-	604	-	ns ns
Rise time	t _r	7	-	137	-	
Turn-off delay time	t _{d(off)}	$V_{CC} = 600 \text{ V}, I_{C} = 300 \text{ A}, R_{q} = 4.7 \Omega,$	-	629	-	
Fall time	t _f	V _{GE} = ± 15 V, T _J = 125 °C	-	167	-	
Turn-on switching loss	E _{on}		-	31.5	-	
Turn-off switching loss	E _{off}	1	-	35.9	-	- mJ
Input capacitance	C _{ies}		-	21.2	-	
Output capacitance	C _{oes}	V _{GE} = 0 V, V _{CE} = 25 V, f = 1.0 MHz	-	1.42	-	nF
Reverse transfer capacitance	C _{res}	1	-	0.94	-	1
SC data	I _{SC}	$t_{sc} \leq 10 \; \mu s, V_{GE} = 15 \; V, T_J = 125 \; ^{\circ}C,$ $V_{CC} = 900 \; V, V_{CEM} \leq 1200 \; V$	-	1800	-	А
Internal gate resistance	R _{gint}		-	1.0	-	Ω
Stray inductance	L _{CE}		-	-	20	nΗ
Module lead resistance, terminal to chip	R _{CC'+EE'}	T _C = 25 °C	-	0.35	-	mΩ

DIODE ELECTRICAL SPECIFICATIONS (T _C = 25 °C unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Diode forward voltage	V _F I _F = 300 A	1 200 A	$T_J = 25 ^{\circ}C$	-	1.82	2.25	V
blode forward voltage		IF = 300 A	T _J = 125 °C	1	1.95	1	
Diode reverse recovery charge	Q _{rr}	Q _{rr}	$T_J = 25 ^{\circ}C$	-	20.2	-	
Diode reverse recovery charge			T _J = 125 °C	-	40.1	-	μC
Diada maak rayaraa raaayam ayarant	I _{rr}	$I_F = 300 \text{ A}, V_R = 600 \text{ V},$ $dI/dt = -2360 \text{ A/}\mu\text{s},$	T _J = 25 °C	-	170	-	Α
Diode peak reverse recovery current		$V_{GE} = -15 \text{ V}$	T _J = 125 °C	-	250	-	A
Diada vayawa vaasyan anavay	E _{rec}	<u> </u>	$T_J = 25 ^{\circ}\text{C}$	-	8.2	-	m l
Diode reverse recovery energy			T _J = 125 °C	-	21.7	-	mJ



THERMAL AND MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Operating junction temperature range	TJ		-	-	150	°C
Storage temperature range	T _{STG}		-40	-	125	C
Junction to case	Р		-	-	0.076	
Diode	R_{thJC}		-	-	0.100	K/W
Case to sink	R _{thCS}	Conductive grease applied	-	0.035	-	
Mounting torque		Power terminal screw: M6 2.5 to 5.0)	Nm	
		Mounting screw: M6	3.0 to 5.0		INIII	
Weight				300		g

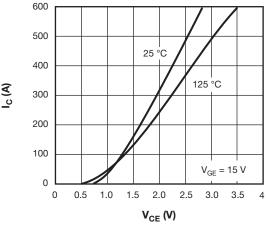


Fig. 1 - IGBT Typical Output Characteristics

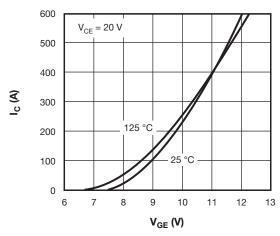


Fig. 2 - IGBT Typical Transfer Characteristics

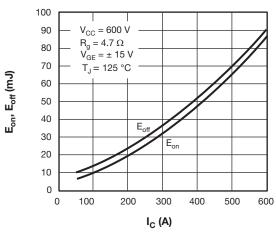


Fig. 3 - IGBT Switching Loss vs. I_C

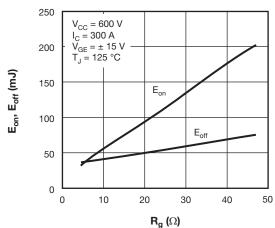
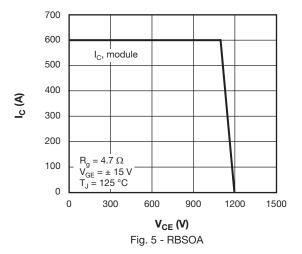


Fig. 4 - IGBT Switching Loss vs. R_q



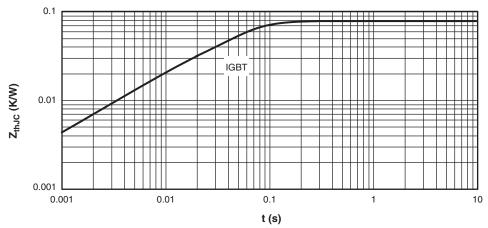


Fig. 6 - IGBT Transient Thermal Impedance

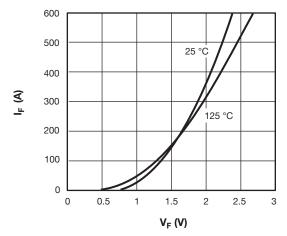


Fig. 7 - Typical Forward Characteristics

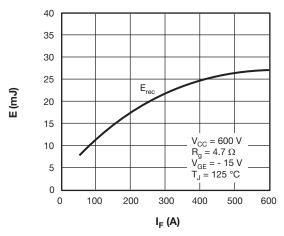


Fig. 8 - Diode Switching Loss vs. I_F

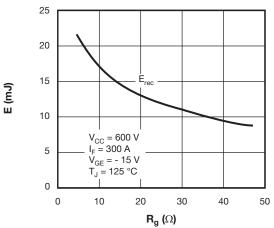


Fig. 9 - Diode Switching Loss vs. Gate Resistance Rg

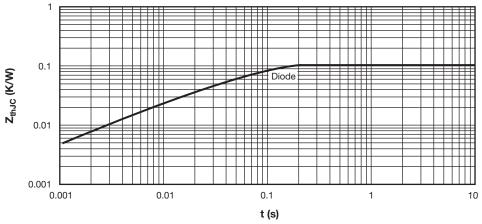
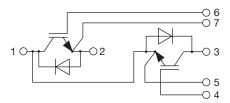


Fig. 10 - Diode Transient Thermal Impedance

CIRCUIT CONFIGURATION

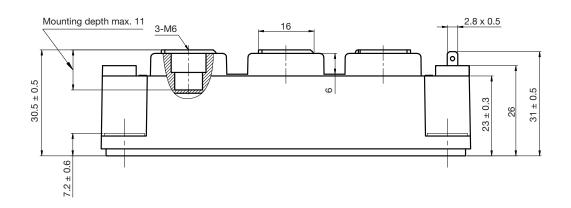


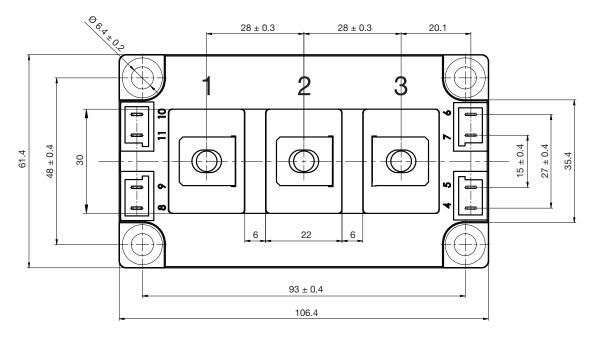
LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95525			



Double INT-A-PAK

DIMENSIONS in millimeters (inches)







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